

LOW CAPACITANCE TVS ARRAY

APPLICATIONS

- ✓ Wireless Communication Circuits
- ✔ RS-422, RS-432 & RS-485
- ✓ Low Voltage ASICs
- ✔ Ethernet 10/100 Base T

IEC COMPATIBILITY (EN61000-4)

- ✔ 61000-4-2 (ESD): Air 15kV, Contact 8kV
- ✔ 61000-4-4 (EFT): 40A 5/50ns
- ✓ 61000-4-5 (Surge): 12A, 8/20µs Level 1 (Line-Ground) & Level 2 (Line-Line)



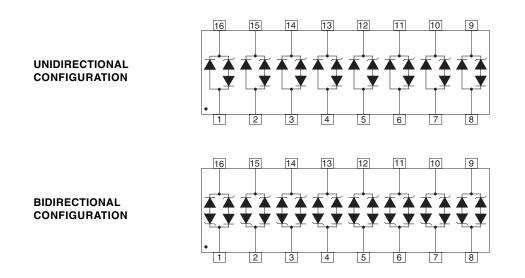
FEATURES

- ✓ 500 Watts Peak Pulse Power per Line (tp=8/20µs)
- ✔ Unidirectional & Bidirectional Configuration
- ✓ ESD Protection > 40 kilovolts
- ✔ Available in Multiple Voltage Types: 3.3V to 36V
- ✓ Protects Up to Eight (8) Lines
- ✔ LOW CAPACITANCE: 15pF

MECHANICAL CHARACTERISTICS

- ✔ Molded JEDEC SO-16 Package
- ✓ Weight 0.15 grams (Approximate)
- ✔ Flammability rating UL 94V-0
- ✓ 16mm Tape and Reel Per EIA Standard 481
- ✔ Marking: Logo, Part Number, Date Code & Pin One Defined By Dot on Top of Package

PINCONFIGURATIONS



DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified							
PARAMETER	SYMBOL	VALUE UNIT:					
Peak Pulse Power ($t_p = 8/20\mu s$) - See Figure 1	P _{PP}	500	Watts				
Operating Temperature	TJ	-55°C to 150°C	°C				
Storage Temperature	T _{STG}	-55°C to 150°C	C°				
Forward Voltage @ 50mA, 300µs - Square Wave (Note 1)	V _F	1.5	Volts				

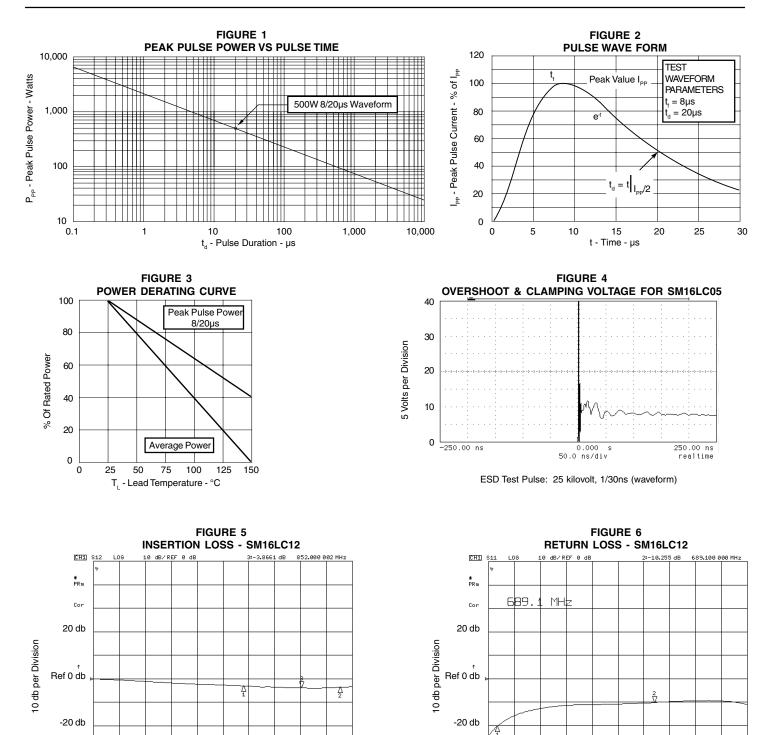
Note 1: Only applies to unidirectional devices.

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified								
PART NUMBER (Notes 1 & 2)	RATED STAND-OFF VOLTAGE	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT	MAXIMUM CAPACITANCE	TEMPERATURE COEFFICIENT OF V _(BR)	
	V _{WM} VOLTS	@ 1mA V _(BR) VOLTS	@ I _p = 1 A V _c VOLTS	@ 8/20µs V _C @ I _{PP}	@V _{wm} Ι _D μΑ	@ 0V, 1 MHz C pF	θV _(BR) mV/°C	
SM16LC03	3.3	4.5	7.0	23.0V @ 43A	125	15	-3	
SM16LC03C	3.3	4.5	7.0	23.0V @ 43A	125	15	-3	
SM16LC05	5.0	6.0	9.8	24.0V @ 42A	20	15	3	
SM16LC05C	5.0	6.0	9.8	24.0V @ 42A	20	15	3	
SM16LC08	8.0	8.5	13.4	26.0V @ 30A	10	15	9	
SM16LC08C	8.0	8.5	13.4	26.0V @ 30A	10	15	9	
SM16LC12	12.0	13.3	19.0	33.0V @ 21A	2	15	16	
SM16LC12C	12.0	13.3	19.0	33.0V @ 21A	2	15	16	
SM16LC15	15.0	16.7	25.5	39.0V @ 15A	2	15	17	
SM16LC15C	15.0	16.7	25.5	39.0V @ 15A	2	15	17	
SM16LC24	24.0	26.7	40.0	57.0V @ 10A	2	15	26	
SM16LC24C	24.0	26.7	40.0	57.0V @ 10A	2	15	26	
SM16LC36	36.0	40.0	53.0	72.0V @ 7.0A	2	15	36	
SM16LC36C	36.0	40.0	53.0	72.0V @ 7.0A	2	15	36	

Note 1: Part numbers with a "C" suffix are bidirectional devices, i.e., SM16LC05<u>C</u>.

Note 2: Unidirectional Devices Only: Do not surge from pins 16 to 1, 15 to 2, 14 to 3, 13 to 4, 12 to 5, 11 to 6, 10 to 7 and 9 to 8. PIV typically greater than 100V for each rectifier diode.

GRAPHS



-50 db

START

50.000 000 MHz

100 MHz per Division

100 MHz per Division

STOP 1 050.000 000 MHz

-50 db

START

50.000 000

APPLICATION NOTE

The SM16LC & SM16LCxxC Series are TVS arrays designed to protect I/O or data lines from the damaging effects of ESD, EFT and other types of surges. This product series provides both unidiretional and bidirectional protection, with a surge capability of 500 Watts P_{pp} per line for an 8/20µs waveform and ESD protection > 40kV.

BIDIRECTIONAL COMMON-MODE CONFIGURATION (Figure 1)

Ideal for RS-485 applications, the SM16LCxxC Series provides up to eight (8) lines of protection in a common-mode configuration as depicted in Figure 1. This low capacitance series allows the transceiver or telecommunications circuit to operate safely without significant signal distortion.

Circuit connectivity is as follows:

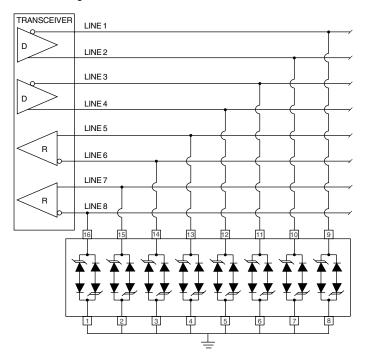
- ✓ Lines 1 is connected to Pin 9.
- ✓ Line 2 is connected to Pin 10.
- ✓ Line 3 is connected to Pin 11.
- ✓ Line 4 is connected to Pin 12.
- ✓ Line 5 is connected to Pin 13.
- ✓ Line 6 is connected to Pin 14.
- ✓ Line 7 is connected to Pin 15.
- ✓ Line 8 is connected to Pin 16.
- ✓ Pins 1-8 are connected to ground.

CIRCUIT BOARD LAYOUT RECOMMENDATIONS

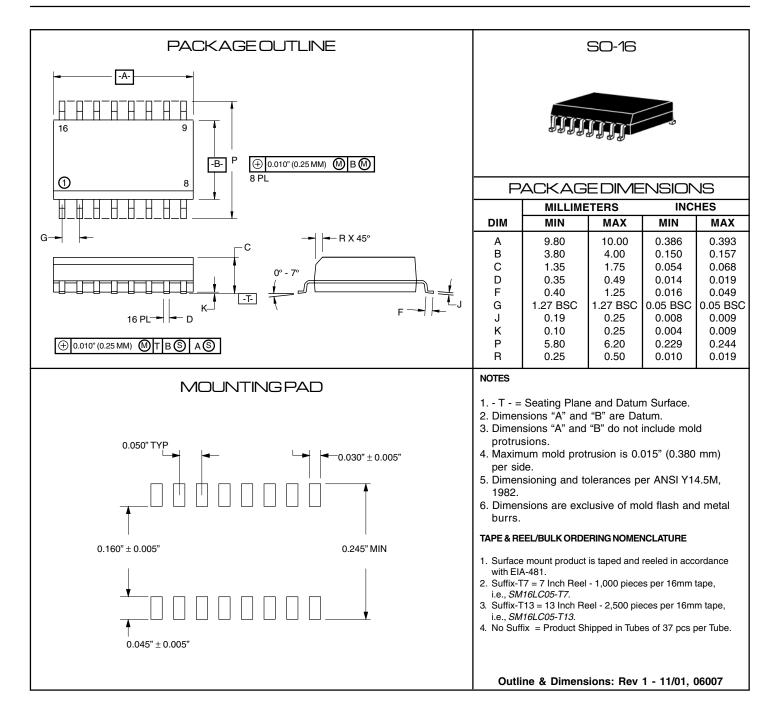
Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- ✓ The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- ✓ The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- ✔ Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

Figure 1. Birectional Common-Mode Protection



PACKAGE OUTLINE & DIMENSIONS



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